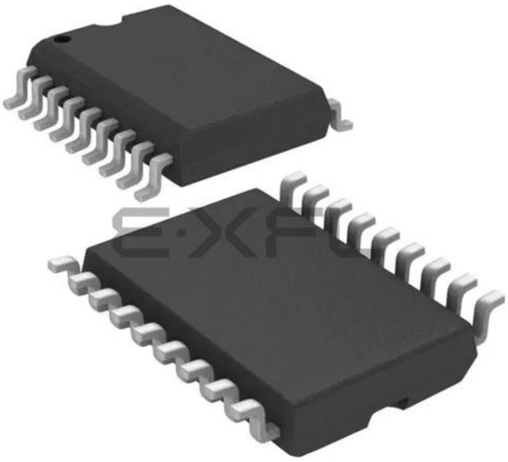
Microchip Technology - PIC16C620-04I/SO Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	896B (512 x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	80 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c620-04i-so

NOTES:

4.2 Data Memory Organization

The data memory (Figure 4-4, Figure 4-5, Figure 4-6 and Figure 4-7) is partitioned into two banks, which contain the General Purpose Registers and the Special Function Registers. Bank 0 is selected when the RP0 bit is cleared. Bank 1 is selected when the RP0 bit (STATUS <5>) is set. The Special Function Registers are located in the first 32 locations of each bank. Register locations 20-7Fh (Bank0) on the PIC16C620A/CR620A/621A and 20-7Fh (Bank0) and A0-BFh (Bank1) on the PIC16C622 and PIC16C622A are General Purpose Registers implemented as static RAM. Some Special Purpose Registers are mapped in Bank 1.

Addresses F0h-FFh of bank1 are implemented as common ram and mapped back to addresses 70h-7Fh in bank0 on the PIC16C620A/621A/622A/CR620A.

4.2.1 GENERAL PURPOSE REGISTER FILE

The register file is organized as 80 x 8 in the PIC16C620/621, 96 x 8 in the PIC16C620A/621A/CR620A and 128 x 8 in the PIC16C622(A). Each is accessed either directly or indirectly through the File Select Register FSR (Section 4.4).

4.2.2 SPECIAL FUNCTION REGISTERS

The Special Function Registers are registers used by the CPU and Peripheral functions for controlling the desired operation of the device (Table 4-1). These registers are static RAM.

The Special Function Registers can be classified into two sets (core and peripheral). The Special Function Registers associated with the "core" functions are described in this section. Those related to the operation of the peripheral features are described in the section of that peripheral feature.

TABLE 4-1: SPECIAL REGISTERS FOR THE PIC16C62X

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR Reset	Value on all other RESETS(1)
Bank 0											
00h	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								xxxx xxxx	xxxx xxxx
01h	TMR0	Timer0 Module's Register								xxxx xxxx	uuuu uuuu
02h	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	0000 0000
03h	STATUS	IRP(2)	RP1(2)	RP0	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Z	DC	C	0001 1xxx	000q quuu
04h	FSR	Indirect data memory address pointer								xxxx xxxx	uuuu uuuu
05h	PORTA	—	—	—	$\overline{\text{RA4}}$	$\overline{\text{RA3}}$	$\overline{\text{RA2}}$	$\overline{\text{RA1}}$	RA0	---x 0000	---u 0000
06h	PORTB	RB7	RB6	RB5	$\overline{\text{RB4}}$	$\overline{\text{RB3}}$	$\overline{\text{RB2}}$	$\overline{\text{RB1}}$	RB0	xxxx xxxx	uuuu uuuu
07h-09h	Unimplemented									—	—
0Ah	PCLATH	—	—	—	Write buffer for upper 5 bits of program counter					---0 0000	---0 0000
0Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	—	CMIF	—	—	—	—	—	—	-0-- ----	-0-- ----
0Dh-1Eh	Unimplemented									—	—
1Fh	CMCON	C2OUT	C1OUT	—	—	CIS	CM2	CM1	CM0	00-- 0000	00-- 0000
Bank 1											
80h	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								xxxx xxxx	xxxx xxxx
81h	OPTION	$\overline{\text{RBPU}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
82h	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	0000 0000
83h	STATUS	IRP(2)	RP1(2)	RP0	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Z	DC	C	0001 1xxx	000q quuu
84h	FSR	Indirect data memory address pointer								xxxx xxxx	uuuu uuuu
85h	TRISA	—	—	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	---1 1111	---1 1111
86h	TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	1111 1111	1111 1111
87h-89h	Unimplemented									—	—
8Ah	PCLATH	—	—	—	Write buffer for upper 5 bits of program counter					---0 0000	---0 0000
8Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
8Ch	PIE1	—	CMIE	—	—	—	—	—	—	-0-- ----	-0-- ----
8Dh	Unimplemented									—	—
8Eh	PCON	—	—	—	—	—	—	$\overline{\text{POR}}$	$\overline{\text{BOR}}$	---- --0x	---- --uq
8Fh-9Eh	Unimplemented									—	—
9Fh	VRCON	VREN	VROE	VRR	—	VR3	VR2	VR1	VR0	000- 0000	000- 0000

Legend: — = Unimplemented locations read as '0', u = unchanged, x = unknown,
q = value depends on condition, shaded = unimplemented

Note 1: Other (non Power-up) Resets include $\overline{\text{MCLR}}$ Reset, Brown-out Reset and Watchdog Timer Reset during normal operation.

2: IRP & RP1 bits are reserved; always maintain these bits clear.

6.2 Using Timer0 with External Clock

When an external clock input is used for Timer0, it must meet certain requirements. The external clock requirement is due to internal phase clock (TOSC) synchronization. Also, there is a delay in the actual incrementing of Timer0 after synchronization.

6.2.1 EXTERNAL CLOCK SYNCHRONIZATION

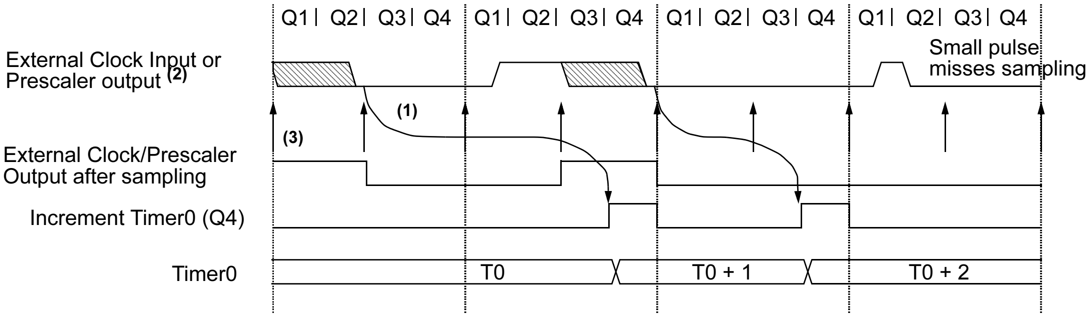
When no prescaler is used, the external clock input is the same as the prescaler output. The synchronization of T0CKI with the internal phase clocks is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks (Figure 6-5). Therefore, it is necessary for T0CKI to be high for at least 2TOSC (and a small RC delay of 20 ns) and low for at least 2TOSC (and a small RC delay of 20 ns). Refer to the electrical specification of the desired device.

When a prescaler is used, the external clock input is divided by the asynchronous ripple-counter type prescaler, so that the prescaler output is symmetrical. For the external clock to meet the sampling requirement, the ripple-counter must be taken into account. Therefore, it is necessary for T0CKI to have a period of at least 4TOSC (and a small RC delay of 40 ns) divided by the prescaler value. The only requirement on T0CKI high and low time is that they do not violate the minimum pulse width requirement of 10 ns. Refer to parameters 40, 41 and 42 in the electrical specification of the desired device.

6.2.2 TIMER0 INCREMENT DELAY

Since the prescaler output is synchronized with the internal clocks, there is a small delay from the time the external clock edge occurs to the time the TMR0 is actually incremented. Figure 6-5 shows the delay from the external clock edge to the timer incrementing.

FIGURE 6-5: TIMER0 TIMING WITH EXTERNAL CLOCK



Note 1: Delay from clock input change to Timer0 increment is 3Tosc to 7Tosc. (Duration of Q = Tosc). Therefore, the error in measuring the interval between two edges on Timer0 input = ±4Tosc max.

2: External clock if no prescaler selected, Prescaler output otherwise.

3: The arrows indicate the points in time where sampling occurs.

6.3.1 SWITCHING PRESCALER ASSIGNMENT

The prescaler assignment is fully under software control (i.e., it can be changed “on-the-fly” during program execution). To avoid an unintended device RESET, the following instruction sequence (Example 6-1) must be executed when changing the prescaler assignment from Timer0 to WDT.)

EXAMPLE 6-1: CHANGING PRESCALER (TIMER0→WDT)

```
 1.BCF      STATUS, RP0    ;Skip if already in
                           ;Bank 0
 2.CLRWDT                  ;Clear WDT
 3.CLRF     TMR0           ;Clear TMR0 & Prescaler
 4.BSF      STATUS, RP0    ;Bank 1
 5.MOVLW    '00101111’b;   ;These 3 lines (5, 6, 7)
 6.MOVWF    OPTION         ;are required only if
                           ;desired PS<2:0> are
 7.CLRWDT                  ;000 or 001
 8.MOVLW    '00101xxx’b    ;Set Postscaler to
 9.MOVWF    OPTION         ;desired WDT rate
10.BCF      STATUS, RP0    ;Return to Bank 0
```

To change prescaler from the WDT to the TMR0 module, use the sequence shown in Example 6-2. This precaution must be taken even if the WDT is disabled.

EXAMPLE 6-2: CHANGING PRESCALER (WDT→TIMER0)

```
 CLRWDT                         ;Clear WDT and
                                ;prescaler
BSF          STATUS, RP0
MOVLW        b'xxxx0xxx'        ;Select TMR0, new
                                ;prescale value and
                                ;clock source
MOVWF        OPTION_REG
BCF         STATUS, RP0
```

TABLE 6-1: REGISTERS ASSOCIATED WITH TIMER0

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on All Other RESETS
01h	TMR0	Timer0 module register								`xxxx xxxx`	`uuuu uuuu`
0Bh/8Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	`0000 000x`	`0000 000u`
81h	OPTION	$\overline{\text{RBPU}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	`1111 1111`	`1111 1111`
85h	TRISA	—	—	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	`---1 1111`	`---1 1111`

Legend: — = Unimplemented locations, read as ‘0’, u = unchanged, x = unknown

Note: Shaded bits are not used by TMR0 module.

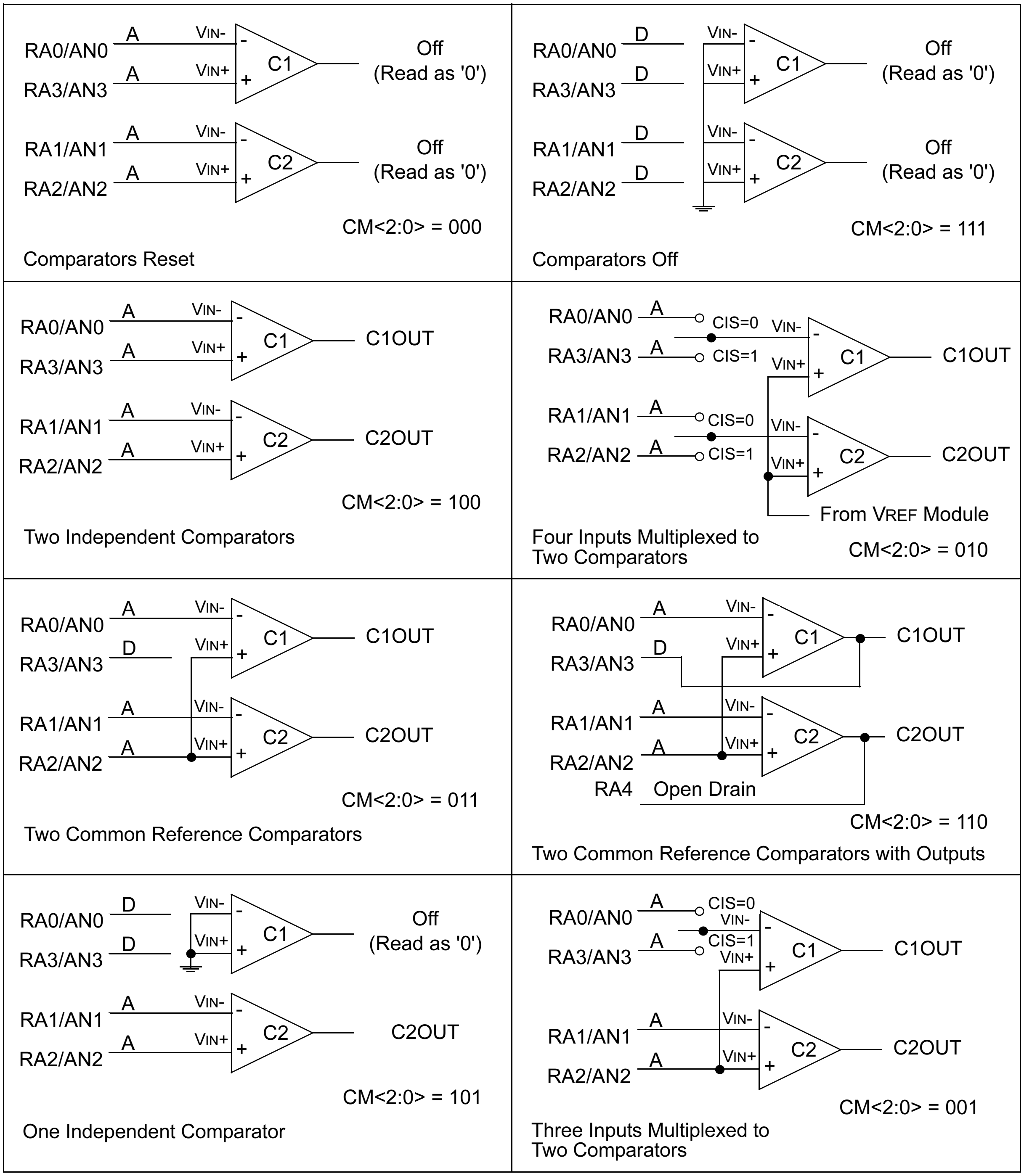
NOTES:

7.1 Comparator Configuration

There are eight modes of operation for the comparators. The CMCON register is used to select the mode. Figure 7-1 shows the eight possible modes. The TRISA register controls the data direction of the comparator pins for each mode. If the Comparator mode is changed, the comparator output level may not be valid for the specified mode change delay shown in Table 12-2.

Note:	Comparator interrupts should be disabled during a Comparator mode change otherwise a false interrupt may occur.

FIGURE 7-1: COMPARATOR I/O OPERATING MODES



A = Analog Input, Port Reads Zeros Always
D = Digital Input
CIS = CMCON<3>, Comparator Input Switch

9.3 RESET

The PIC16C62X differentiates between various kinds of RESET:

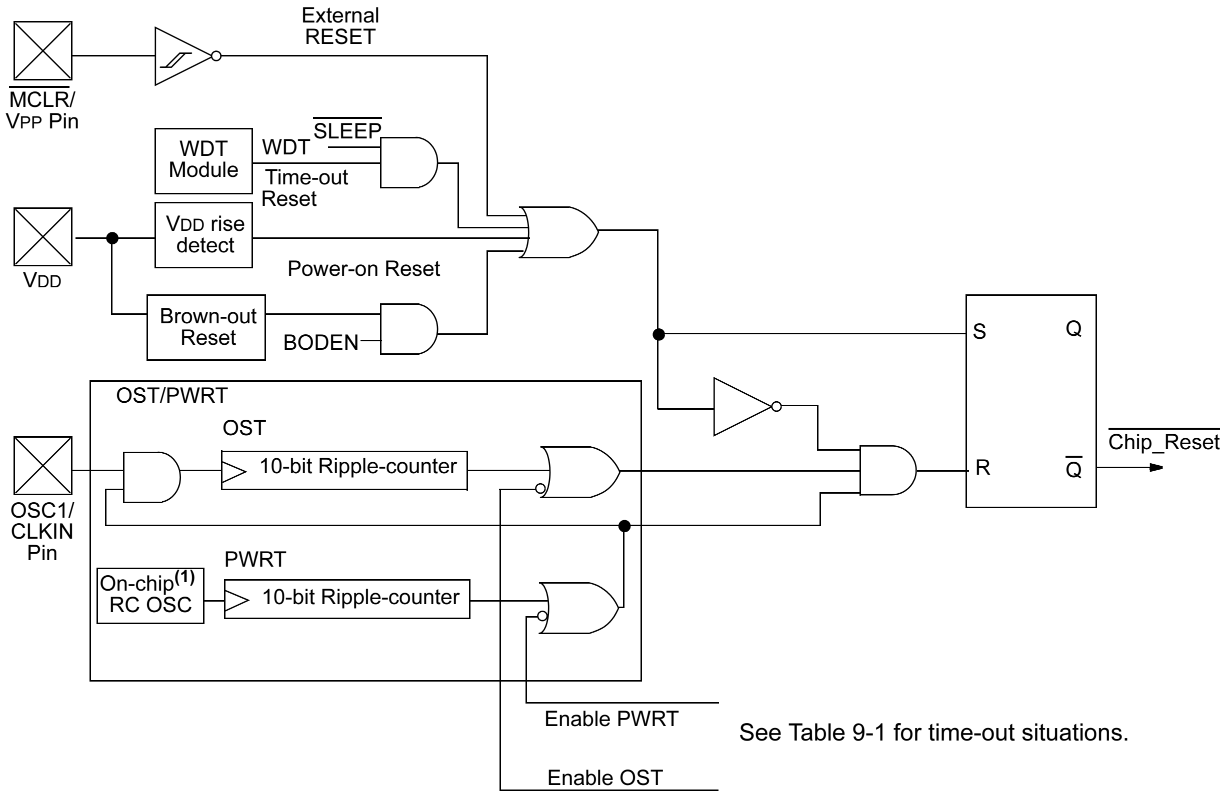
a) Power-on Reset (POR)
b) $\overline{\text{MCLR}}$ Reset during normal operation
c) $\overline{\text{MCLR}}$ Reset during SLEEP
d) WDT Reset (normal operation)
e) WDT wake-up (SLEEP)
f) Brown-out Reset (BOR)

Some registers are not affected in any RESET condition Their status is unknown on POR and unchanged in any other RESET. Most other registers are reset to a “RESET state” on Power-on Reset, $\overline{\text{MCLR}}$ Reset, WDT Reset and $\overline{\text{MCLR}}$ Reset during SLEEP. They are not affected by a WDT wake-up, since this is viewed as the resumption of normal operation. $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits are set or cleared differently in different RESET situations as indicated in Table 9-2. These bits are used in software to determine the nature of the RESET. See Table 9-5 for a full description of RESET states of all registers.

A simplified block diagram of the on-chip RESET circuit is shown in Figure 9-6.

The $\overline{\text{MCLR}}$ Reset path has a noise filter to detect and ignore small pulses. See Table 12-5 for pulse width specification.

FIGURE 9-6: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



See Table 9-1 for time-out situations.

Note 1: This is a separate oscillator from the RC oscillator of the CLKIN pin.

9.9 Code Protection

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out for verification purposes.

Note: Microchip does not recommend code protecting windowed devices.

9.10 ID Locations

Four memory locations (2000h-2003h) are designated as ID locations where the user can store checksum or other code identification numbers. These locations are not accessible during normal execution, but are readable and writable during Program/Verify. Only the Least Significant 4 bits of the ID locations are used.

9.11 In-Circuit Serial Programming™

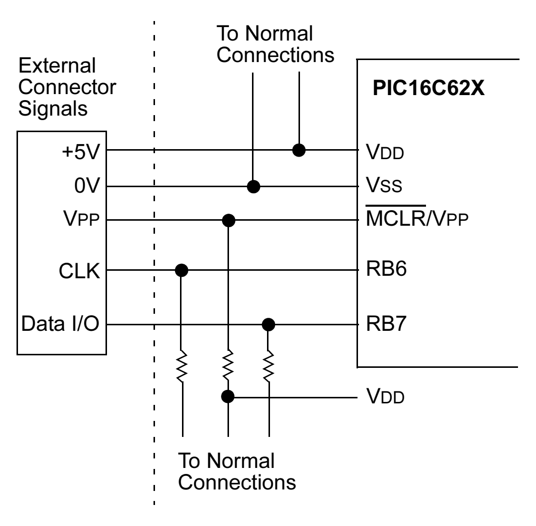
The PIC16C62X microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data and three other lines for power, ground and the programming voltage. This allows customers to manufacture boards with unprogrammed devices and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

The device is placed into a Program/Verify mode by holding the RB6 and RB7 pins low, while raising the $\overline{MCLR}$ (V_{PP}) pin from V_{IL} to V_{IHH} (see programming specification). RB6 becomes the programming clock and RB7 becomes the programming data. Both RB6 and RB7 are Schmitt Trigger inputs in this mode.

After RESET, to place the device into Programming/ Verify mode, the program counter (PC) is at location 00h. A 6-bit command is then supplied to the device. Depending on the command, 14-bits of program data are then supplied to or from the device, depending if the command was a load or a read. For complete details of serial programming, please refer to the PIC16C6X/7X/9XX Programming Specification (DS30228).

A typical In-Circuit Serial Programming connection is shown in Figure 9-19.

FIGURE 9-19: TYPICAL IN-CIRCUIT SERIAL PROGRAMMING CONNECTION



BTFSS	**Bit Test f, Skip if Set**
Syntax:	[*label*] BTFSS f,b
Operands:	$0 \le f \le 127$ $0 \le b < 7$
Operation:	skip if (f<b>) = 1
Status Affected:	None
Encoding:	`01` | `11bb` | `bfff` | `ffff`
Description:	If bit 'b' in register 'f' is '1', then the next instruction is skipped. If bit 'b' is '1', then the next instruction fetched during the current instruction execution, is discarded and a `NOP` is executed instead, making this a two-cycle instruction.
Words:	1
Cycles:	1(2)

Example

```
HERE     BTFSS    FLAG,1
FALSE    GOTO     PROCESS_CODE
TRUE     •
         •
         •
```

Before Instruction
PC = address `HERE`
After Instruction
if FLAG<1> = 0,
PC = address `FALSE`
if FLAG<1> = 1,
PC = address `TRUE`

CALL	**Call Subroutine**
Syntax:	[*label*] CALL k
Operands:	$0 \le k \le 2047$
Operation:	(PC)+ 1→ TOS, k → PC<10:0>, (PCLATH<4:3>) → PC<12:11>
Status Affected:	None
Encoding:	`10` | `0kkk` | `kkkk` | `kkkk`
Description:	Call Subroutine. First, return address (PC+1) is pushed onto the stack. The eleven bit immediate address is loaded into PC bits <10:0>. The upper bits of the PC are loaded from PCLATH. `CALL` is a two-cycle instruction.
Words:	1
Cycles:	2

Example

```
HERE     CALL     THERE
```

Before Instruction
PC = Address `HERE`
After Instruction
PC = Address `THERE`
TOS = Address `HERE+1`

CLRF	**Clear f**
Syntax:	[*label*] CLRF f
Operands:	$0 \le f \le 127$
Operation:	00h → (f) 1 → Z
Status Affected:	Z
Encoding:	`00` | `0001` | `1fff` | `ffff`
Description:	The contents of register 'f' are cleared and the Z bit is set.
Words:	1
Cycles:	1

Example

```
CLRF     FLAG_REG
```

Before Instruction
FLAG_REG = 0x5A
After Instruction
FLAG_REG = 0x00
Z = 1

11.14 PICDEM 1 PICmicro Demonstration Board

The PICDEM 1 demonstration board demonstrates the capabilities of the PIC16C5X (PIC16C54 to PIC16C58A), PIC16C61, PIC16C62X, PIC16C71, PIC16C8X, PIC17C42, PIC17C43 and PIC17C44. All necessary hardware and software is included to run basic demo programs. The sample microcontrollers provided with the PICDEM 1 demonstration board can be programmed with a PRO MATE II device programmer, or a PICSTART Plus development programmer. The PICDEM 1 demonstration board can be connected to the MPLAB ICE in-circuit emulator for testing. A prototype area extends the circuitry for additional application components. Features include an RS-232 interface, a potentiometer for simulated analog input, push button switches and eight LEDs.

11.15 PICDEM.net Internet/Ethernet Demonstration Board

The PICDEM.net demonstration board is an Internet/ Ethernet demonstration board using the PIC18F452 microcontroller and TCP/IP firmware. The board supports any 40-pin DIP device that conforms to the standard pinout used by the PIC16F877 or PIC18C452. This kit features a user friendly TCP/IP stack, web server with HTML, a 24L256 Serial EEPROM for Xmodem download to web pages into Serial EEPROM, ICSP/MPLAB ICD 2 interface connector, an Ethernet interface, RS-232 interface, and a 16 x 2 LCD display. Also included is the book and CD-ROM *"TCP/IP Lean, Web Servers for Embedded Systems,"* by Jeremy Bentham

11.16 PICDEM 2 Plus Demonstration Board

The PICDEM 2 Plus demonstration board supports many 18-, 28-, and 40-pin microcontrollers, including PIC16F87X and PIC18FXX2 devices. All the necessary hardware and software is included to run the demonstration programs. The sample microcontrollers provided with the PICDEM 2 demonstration board can be programmed with a PRO MATE II device programmer, PICSTART Plus development programmer, or MPLAB ICD 2 with a Universal Programmer Adapter. The MPLAB ICD 2 and MPLAB ICE in-circuit emulators may also be used with the PICDEM 2 demonstration board to test firmware. A prototype area extends the circuitry for additional application components. Some of the features include an RS-232 interface, a 2 x 16 LCD display, a piezo speaker, an on-board temperature sensor, four LEDs, and sample PIC18F452 and PIC16F877 FLASH microcontrollers.

11.17 PICDEM 3 PIC16C92X Demonstration Board

The PICDEM 3 demonstration board supports the PIC16C923 and PIC16C924 in the PLCC package. All the necessary hardware and software is included to run the demonstration programs.

11.18 PICDEM 4 8/14/18-Pin Demonstration Board

The PICDEM 4 can be used to demonstrate the capabilities of the 8-, 14-, and 18-pin PIC16XXXX and PIC18XXXX MCUs, including the PIC16F818/819, PIC16F87/88, PIC16F62XA and the PIC18F1320 family of microcontrollers. PICDEM 4 is intended to showcase the many features of these low pin count parts, including LIN and Motor Control using ECCP. Special provisions are made for low power operation with the supercapacitor circuit, and jumpers allow on-board hardware to be disabled to eliminate current draw in this mode. Included on the demo board are provisions for Crystal, RC or Canned Oscillator modes, a five volt regulator for use with a nine volt wall adapter or battery, DB-9 RS-232 interface, ICD connector for programming via ICSP and development with MPLAB ICD 2, 2x16 liquid crystal display, PCB footprints for H-Bridge motor driver, LIN transceiver and EEPROM. Also included are: header for expansion, eight LEDs, four potentiometers, three push buttons and a prototyping area. Included with the kit is a PIC16F627A and a PIC18F1320. Tutorial firmware is included along with the User's Guide.

11.19 PICDEM 17 Demonstration Board

The PICDEM 17 demonstration board is an evaluation board that demonstrates the capabilities of several Microchip microcontrollers, including PIC17C752, PIC17C756A, PIC17C762 and PIC17C766. A programmed sample is included. The PRO MATE II device programmer, or the PICSTART Plus development programmer, can be used to reprogram the device for user tailored application development. The PICDEM 17 demonstration board supports program download and execution from external on-board FLASH memory. A generous prototype area is available for user hardware expansion.

NOTES:

12.2 DC Characteristics: PIC16C62XA-04 (Commercial, Industrial, Extended)
PIC16C62XA-20 (Commercial, Industrial, Extended)
PIC16LC62XA-04 (Commercial, Industrial, Extended)

PIC16C62XA	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended
PIC16LC62XA	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended

Param. No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D001	VDD	Supply Voltage	3.0	—	5.5	V	See Figures 12-1, 12-2, 12-3, 12-4, and 12-5
D001	VDD	Supply Voltage	2.5	—	5.5	V	See Figures 12-1, 12-2, 12-3, 12-4, and 12-5
D002	VDR	RAM Data Retention Voltage(1)	—	1.5*	—	V	Device in SLEEP mode
D002	VDR	RAM Data Retention Voltage(1)	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in Active Operation mode are:
$\overline{\text{OSC1}}$ = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula: Ir = VDD/2REXT (mA) with REXT in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.

12.2 DC Characteristics: PIC16C62XA-04 (Commercial, Industrial, Extended)
PIC16C62XA-20 (Commercial, Industrial, Extended)
PIC16LC62XA-04 (Commercial, Industrial, Extended) (CONT.)

<table>
<tr><td colspan="3">PIC16C62XA</td><td colspan="5">Standard Operating Conditions (unless otherwise stated)
Operating temperature -40°C ≤ TA ≤ +85°C for industrial and
0°C ≤ TA ≤ +70°C for commercial and
-40°C ≤ TA ≤ +125°C for extended</td></tr>
<tr><td colspan="3">PIC16LC62XA</td><td colspan="5">Standard Operating Conditions (unless otherwise stated)
Operating temperature -40°C ≤ TA ≤ +85°C for industrial and
0°C ≤ TA ≤ +70°C for commercial and
-40°C ≤ TA ≤ +125°C for extended</td></tr>
<tr><th>Param. No.</th><th>Sym</th><th>Characteristic</th><th>Min</th><th>Typ†</th><th>Max</th><th>Units</th><th>Conditions</th></tr>
<tr><td>D010</td><td>IDD</td><td>Supply Current(2, 4)</td><td>—</td><td>1.2</td><td>2.0</td><td>mA</td><td>FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT mode, (Note 4)*</td></tr>
<tr><td></td><td></td><td></td><td>—</td><td>0.4</td><td>1.2</td><td>mA</td><td>FOSC = 4 MHz, VDD = 3.0V, WDT disabled, XT mode, (Note 4)*</td></tr>
<tr><td></td><td></td><td></td><td>—</td><td>1.0</td><td>2.0</td><td>mA</td><td>FOSC = 10 MHz, VDD = 3.0V, WDT disabled, HS mode, (Note 6)</td></tr>
<tr><td></td><td></td><td></td><td>—</td><td>4.0</td><td>6.0</td><td>mA</td><td>FOSC = 20 MHz, VDD = 4.5V, WDT disabled, HS mode</td></tr>
<tr><td></td><td></td><td></td><td>—</td><td>4.0</td><td>7.0</td><td>mA</td><td>FOSC = 20 MHz, VDD = 5.5V, WDT disabled*, HS mode</td></tr>
<tr><td></td><td></td><td></td><td>—</td><td>35</td><td>70</td><td>µA</td><td>FOSC = 32 kHz, VDD = 3.0V, WDT disabled, LP mode</td></tr>
<tr><td>D010</td><td>IDD</td><td>Supply Current(2)</td><td>—</td><td>1.2</td><td>2.0</td><td>mA</td><td>FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT mode, (Note 4)*</td></tr>
<tr><td></td><td></td><td></td><td>—</td><td>—</td><td>1.1</td><td>mA</td><td>FOSC = 4 MHz, VDD = 2.5V, WDT disabled, XT mode, (Note 4)</td></tr>
<tr><td></td><td></td><td></td><td>—</td><td>35</td><td>70</td><td>µA</td><td>FOSC = 32 kHz, VDD = 2.5V, WDT disabled, LP mode</td></tr>
<tr><td>D020</td><td>IPD</td><td>Power-down Current(3)</td><td>—</td><td>—</td><td>2.2</td><td>µA</td><td>VDD = 3.0V</td></tr>
<tr><td></td><td></td><td></td><td>—</td><td>—</td><td>5.0</td><td>µA</td><td>VDD = 4.5V*</td></tr>
<tr><td></td><td></td><td></td><td>—</td><td>—</td><td>9.0</td><td>µA</td><td>VDD = 5.5V</td></tr>
<tr><td></td><td></td><td></td><td>—</td><td>—</td><td>15</td><td>µA</td><td>VDD = 5.5V Extended Temp.</td></tr>
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<tr><td></td><td></td><td></td><td>—</td><td>—</td><td>9.0</td><td>µA</td><td>VDD = 5.5V</td></tr>
<tr><td></td><td></td><td></td><td>—</td><td>—</td><td>15</td><td>µA</td><td>VDD = 5.5V Extended Temp.</td></tr>
</table>

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in Active Operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula: Ir = VDD/2REXT (mA) with REXT in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.

12.5 DC CHARACTERISTICS: PIC16C620A/C621A/C622A-40[7] (Commercial) PIC16CR620A-40[7] (Commercial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for commercial				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	VDD	Supply Voltage	3.0	—	5.5	V	FOSC = DC to 20 MHz
D002	VDR	RAM Data Retention Voltage(1)	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05 *	—	—	V/ms	See section on Power-on Reset for details
D005	VBOR	Brown-out Detect Voltage	3.65	4.0	4.35	V	BOREN configuration bit is cleared
D010	IDD	Supply Current(2,4)	—	1.2	2.0	mA	FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT OSC mode, **(Note 4)***
			—	0.4	1.2	mA	FOSC = 4 MHz, VDD = 3.0V, WDT disabled, XT OSC mode, **(Note 4)**
			—	1.0	2.0	mA	FOSC = 10 MHz, VDD = 3.0V, WDT disabled, HS OSC mode, **(Note 6)**
			—	4.0	6.0	mA	FOSC = 20 MHz, VDD = 4.5V, WDT disabled, HS OSC mode
			—	4.0	7.0	mA	FOSC = 20 MHz, VDD = 5.5V, WDT disabled*, HS OSC mode
			—	35	70	µA	FOSC = 32 kHz, VDD = 3.0V, WDT disabled, LP OSC mode
D020	IPD	Power Down Current(3)	—	—	2.2	µA	VDD = 3.0V
			—	—	5.0	µA	VDD = 4.5V*
			—	—	9.0	µA	VDD = 5.5V
			—	—	15	µA	VDD = 5.5V Extended
D022	ΔIWDT	WDT Current(5)	—	6.0	10	µA	VDD = 4.0V
					12	µA	(125°C)
D022A	ΔIBOR	Brown-out Reset Current(5)	—	75	125	µA	$\overline{\text{BOD}}$ enabled, VDD = 5.0V
D023	ΔICOMP	Comparator Current for each Comparator(5)	—	30	60	µA	VDD = 4.0V
D023A	ΔIVREF	VREF Current(5)	—	80	135	µA	VDD = 4.0V
	ΔIEE Write	Operating Current	—		3	mA	VCC = 5.5V, SCL = 400 kHz
	ΔIEE Read	Operating Current	—		1	mA	
	ΔIEE	Standby Current	—		30	µA	VCC = 3.0V, EE VDD = VCC
	ΔIEE	Standby Current	—		100	µA	VCC = 3.0V, EE VDD = VCC
1A	FOSC	LP Oscillator Operating Frequency	0	—	200	kHz	All temperatures
		RC Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		XT Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		HS Oscillator Operating Frequency	0	—	20	MHz	All temperatures

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in Active Operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD, $\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC OSC configuration, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kΩ.

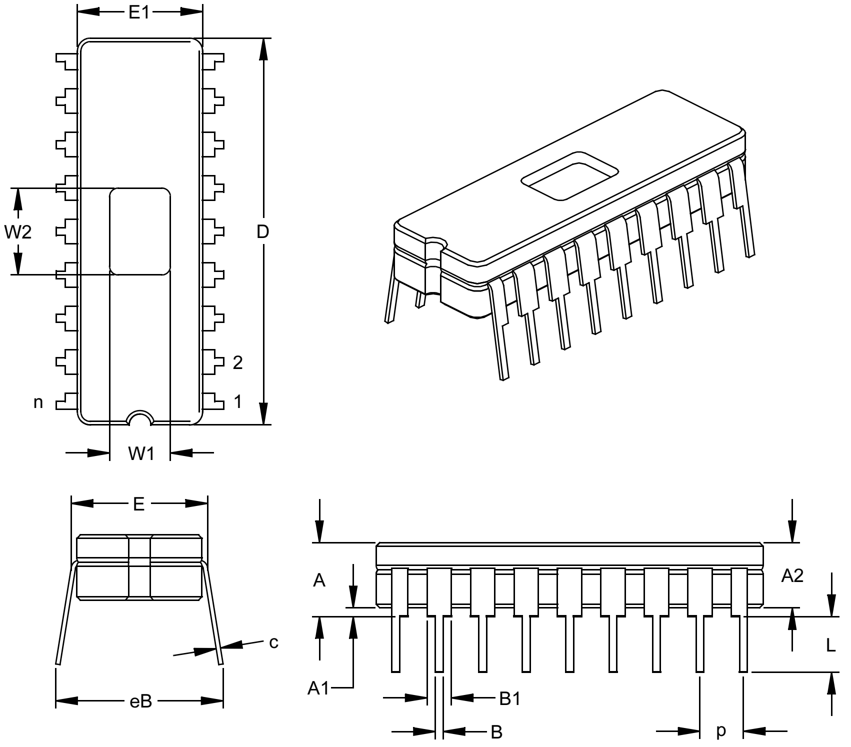
5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.

7: See Section 12.1 and Section 12.3 for 16C62X and 16CR62X devices for operation between 20 MHz and 40 MHz for valid modified characteristics.

14.0 PACKAGING INFORMATION

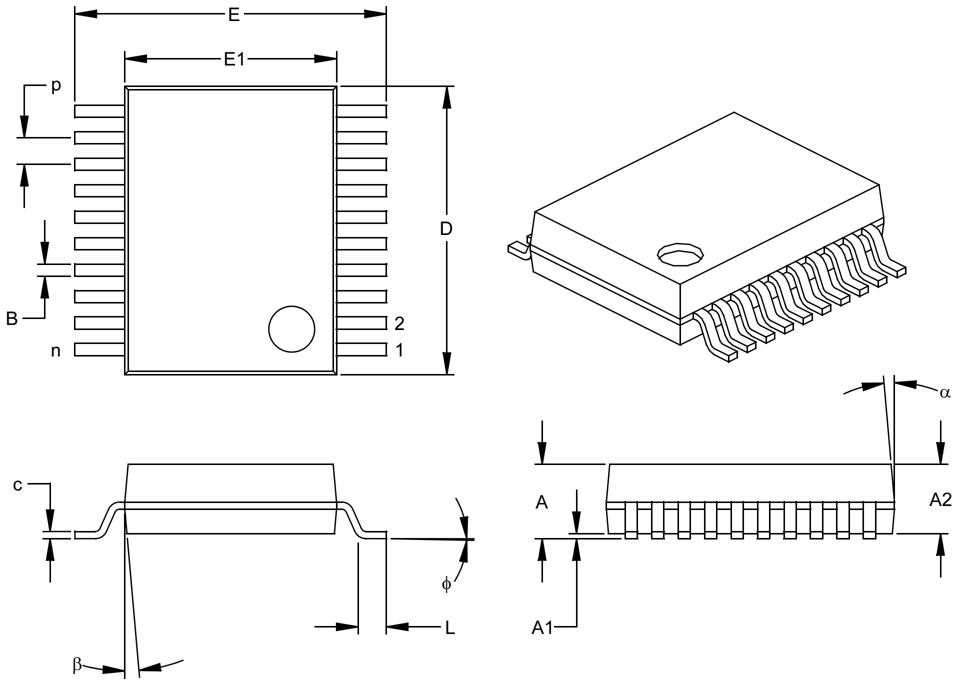
18-Lead Ceramic Dual In-line with Window (JW) – 300 mil (CERDIP)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.170	.183	.195	4.32	4.64	4.95
Ceramic Package Height	A2	.155	.160	.165	3.94	4.06	4.19
Standoff	A1	.015	.023	.030	0.38	0.57	0.76
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Ceramic Pkg. Width	E1	.285	.290	.295	7.24	7.37	7.49
Overall Length	D	.880	.900	.920	22.35	22.86	23.37
Tip to Seating Plane	L	.125	.138	.150	3.18	3.49	3.81
Lead Thickness	c	.008	.010	.012	0.20	0.25	0.30
Upper Lead Width	B1	.050	.055	.060	1.27	1.40	1.52
Lower Lead Width	B	.016	.019	.021	0.41	0.47	0.53
Overall Row Spacing §	eB	.345	.385	.425	8.76	9.78	10.80
Window Width	W1	.130	.140	.150	3.30	3.56	3.81
Window Length	W2	.190	.200	.210	4.83	5.08	5.33

* Controlling Parameter
§ Significant Characteristic
JEDEC Equivalent: MO-036
Drawing No. C04-010

20-Lead Plastic Shrink Small Outline (SS) – 209 mil, 5.30 mm (SSOP)



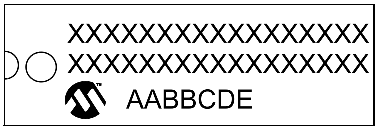
Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		20			20	
Pitch	p		.026			0.65	
Overall Height	A	.068	.073	.078	1.73	1.85	1.98
Molded Package Thickness	A2	.064	.068	.072	1.63	1.73	1.83
Standoff §	A1	.002	.006	.010	0.05	0.15	0.25
Overall Width	E	.299	.309	.322	7.59	7.85	8.18
Molded Package Width	E1	.201	.207	.212	5.11	5.25	5.38
Overall Length	D	.278	.284	.289	7.06	7.20	7.34
Foot Length	L	.022	.030	.037	0.56	0.75	0.94
Lead Thickness	c	.004	.007	.010	0.10	0.18	0.25
Foot Angle	φ	0	4	8	0.00	101.60	203.20
Lead Width	B	.010	.013	.015	0.25	0.32	0.38
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter
§ Significant Characteristic

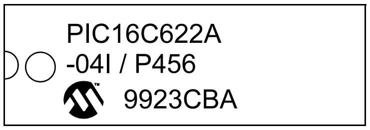
Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MO-150
Drawing No. C04-072

14.1 Package Marking Information

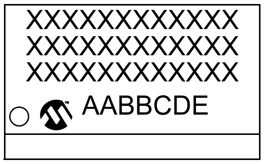
18-Lead PDIP



Example



18-Lead SOIC (.300")



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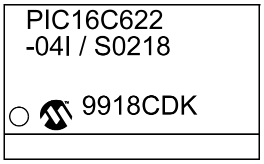
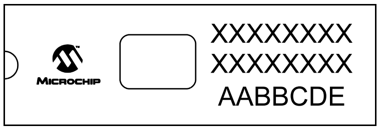


18-Lead CERDIP Windowed



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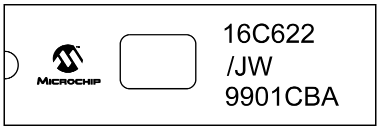
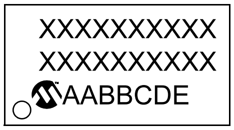
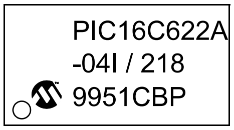


20-Lead SSOP



Example



Legend:		
	XX...X	Customer specific information*
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.

* Standard PICmicro device marking consists of Microchip part number, year code, week code, and traceability code. For PICmicro device marking beyond this, certain price adders apply. Please check with your Microchip Sales Office. For QTP devices, any special marking adders are included in QTP price.

NOTES:

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